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(54) **MANUFACTURING PROCESS OF
RIGID-FLEX BOARD**

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(57) **ABSTRACT**

A rigid-flex board is manufactured by attaching multiple self-adhesive copper foil films to a flexible circuit board through multiple build-up processes, thereby eliminating the need to pre-fabricate a rigid board and slot the rigid board. The build-up processes of the self-adhesive copper foil films allow the resulting rigid boards to be highly uniform in thickness so that thickness deviation of the rigid-flex board can be reduced.

